LP873347 Technical Reference Manual

This document provides the register bit values for the one-time programmable (OTP) bits of the orderable part number, LP873347RHDR / LP873347RHDT.

1 Introduction

This technical reference manual can be used as a reference for the LP873347 default register bits after OTP memory download. This technical reference manual does not provide information about the electrical characteristics, external components, package, or the functionality of the device. For this information and the full register map, refer to the *LP8733xx Dual High-Current Buck Converter and Dual Linear Regulator* data sheet.

2 OTP Memory Device Settings

This section lists all of the device settings that are downloaded from OTP memory.

Table 1 lists the device settings for I²C and OTP revision ID values.

Table 1. Device Identification and I²C Settings

	Description	Bit Name	LP873347
I²C address			60h
DEVICE_ID	Device specific ID code	DEVICE_ID	0h
OTP_ID	Identification code for OTP version	OTP_ID	47h

Table 2 lists the device settings for BUCK0 and BUCK1. The maximum allowed slew-rate for BUCKx depends on the output capacitance. Refer to the for output capacitance boundary conditions.

Table 2. BUCK0 and BUCK1 OTP Settings

	Description	Bit Name	LP873347
	Buck phase configuration (2 single phase Bucks or combined 2 phase, denoted as 1+1 or 2-phase)		1+1
	Switching frequency		2 MHz
	Spread spectrum	EN_SPREAD_SPEC	Disabled
BUCK0	Output voltage	BUCK0_VSET	0.90 V
	Enable, EN-pin or I²C register	BUCK0_EN_PIN_CTRL	EN-pin
	Control for BUCK0	BUCK0_EN	High
	Force PWM mode or auto mode	BUCK0_FPWM	Auto mode
	Peak current limit	BUCK0_ILIM	4.0 A
	Maximum load current limit	NA	3 A
	Slew rate	BUCK0_SLEW_RATE	3.8 mV/us
	Startup delay	BUCK0_STARTUP_DELAY	0 ms
	Shutdown delay	BUCK0_SHUTDOWN_DELAY	12 ms

Table 2. BUCK0 and BUCK1 OTP Settings (continued)

	Description	Bit Name	LP873347
BUCK1	Output voltage	BUCK1_VSET	0.95 V
	Enable, EN-pin or I²C register	BUCK1_EN_PIN_CTRL	EN-pin
	Control for BUCK1	BUCK1_EN	High
	Force PWM mode or auto mode	BUCK1_FPWM	Auto mode
	Peak current limit	BUCK1_ILIM	4.0 A
	Maximum load current limit	NA	3 A
	Slew rate	BUCK1_SLEW_RATE	3.8 mV/us
	Startup delay	BUCK1_STARTUP_DELAY	2 ms
	Shutdown delay	BUCK1_SHUTDOWN_DELAY	10 ms

Table 3 lists the device settings for LDO0 and LDO1.

Table 3. LDO0 and LDO1 OTP Settings

	Description	Bit Name	LP873347
LDO0	Output voltage	LDO0_VSET	1.200 V
	Enable, EN-pin or I²C register	LDO0_EN_PIN_CTRL	EN-pin
	Control for LDO0	LDO0_EN	High
	Startup delay	LDO0_STARTUP_DELAY	12 ms
	Shutdown delay	LDO0_SHUTDOWN_DELAY	0 ms
LDO1	Output voltage	LDO1_VSET	0.90 V
	Enable, EN-pin or I²C register	LDO1_EN_PIN_CTRL	EN-pin
	Control for LDO1	LDO1_EN	High
	Startup delay	LDO1_STARTUP_DELAY	0 ms
	Shutdown delay	LDO1_SHUTDOWN_DELAY	12 ms

Table 4 lists the device settings for GPIOs.

Table 4. EN, CLKIN and GPIO Pin Settings

	Description	Bit Name	LP873347
EN pin	EN pin pulldown resistor enable or disable	EN_PD	Enabled
CLKIN pin	CLKIN or GPO2 mode selection	CLKIN_PIN_SEL	GPO2
	CLKIN pin pulldown resistor enable or disable (applicable for both CLKIN and GPO2 modes)	CLKIN_PD	Enabled
	Frequency of external clock when connected to CLKIN	EXT_CLK_FREQ	2 MHz
	Enable for the internal PLL. When PLL disabled, internal RC OSC is used	EN_PLL	Disabled
GPO	GPO output type (push-pull or open drain)	GPO_OD	OD
	Enable, EN-pin or I²C register	GPO_EN_PIN_CTRL	EN-pin
	Control for GPO	GPO_EN	High
	Startup delay	GPO_ STARTUP_ DELAY	1 ms
	Shutdown delay	GPO_ SHUTDOWN_ DELAY	12 ms
GPO2	GPO2 output type (push-pull or open drain)	GPO2_OD	OD
	Enable, EN-pin or I²C register	GPO2_EN_PIN_CTRL	I2C
	Control for GPO2	GPO2_EN	Low
	Startup delay	GPO2_ STARTUP_ DELAY	0 ms
	Shutdown delay	GPO2_ SHUTDOWN_ DELAY	0 ms

Table 5 lists the device PGOOD settings.

Table 5. PGOOD OTP Settings

	Description	Bit Name	LP873347
Signals monitored by PGOOD	BUCK0 output voltage	EN_PGOOD_BUCK0	Yes
	BUCK1 output voltage	EN_PGOOD_BUCK1	Yes
	LDO0 output voltage	EN_PGOOD_LDO0	Yes
	LDO1 output voltage	EN_PGOOD_LDO1	Yes
	Thermal warning	EN_PGOOD_TWARN	No
PGOOD mode selections	PGOOD thresholds for BUCK0, BUCK1 (Undervoltage / Window (undervoltage and overvoltage))	PGOOD_WINDOW_BUCK	Window
	PGOOD thresholds for LDO0, LDO1 (Undervoltage / Window (undervoltage and overvoltage))	PGOOD_WINDOW_LDO	Window
	PGOOD operating mode (detecting UNUSUAL situations / detecting UNVALID situations)	PGOOD_MODE	Detecting UNUSUAL situations
	PGOOD signal mode (status / latched until fault source read)	PG_FAULT_GATES_PGOOD	Status
	PGOOD output mode (push-pull or open drain)	PGOOD_OD	OD
	PGOOD polarity (active high/ active low)	PGOOD_POL	Valid level high

Table 6 lists the device protection settings.

Table 6. Protections OTP Settings

	Description	Bit Name	LP873347
Protections	Thermal warning level (125°C or 137°C)	TDIE_WARN_LEVEL	125°C
	Input overvoltage protection	NA	Enabled

Table 7 lists the device settings for interrupts. When an interrupt from an event is unmasked, an interrupt is generated on the nINT pin.

Table 7. Interrupt Mask Settings

	Interrupt event	Bit Name	LP873347
General	PGOOD pin changing active to inactive	PGOOD_INT_MASK	Masked
	Sync clock appears or disappears	SYNC_CLK_MASK	Masked
	Thermal warning	TDIE_WRN_MASK	Masked
	Load measurement ready	I_MEAS_MASK	Masked
	Register reset	RESET_REG_MASK	Masked
BUCK0	Buck0 PGood active	BUCK0_PGR_MASK	Masked
	Buck0 PGood inactive	BUCK0_PGF_MASK	Masked
	Buck0 current limit	BUCK0_ILIM_MASK	Masked
BUCK1	Buck1 PGood active	BUCK1_PGR_MASK	Masked
	Buck1 PGood inactive	BUCK1_PGF_MASK	Masked
	Buck1 current limit	BUCK1_ILIM_MASK	Masked
LDO0	LDO0 PGood active	LDO0_PGR_MASK	Masked
	LDO0 PGood inactive	LDO0_PGF_MASK	Masked
	LDO0 current limit	LDO0_ILIM_MASK	Masked
LDO1	LDO1 PGood active	LDO1_PGR_MASK	Masked
	LDO1 PGood inactive	LDO1_PGF_MASK	Masked
	LDO1 current limit	LDO1_ILIM_MASK	Masked

3 Power-up and Power Down Sequence

This section shows the power-up and power-down sequence for the device. The power-up and power-down delays for each rail are shown in Figure 1.

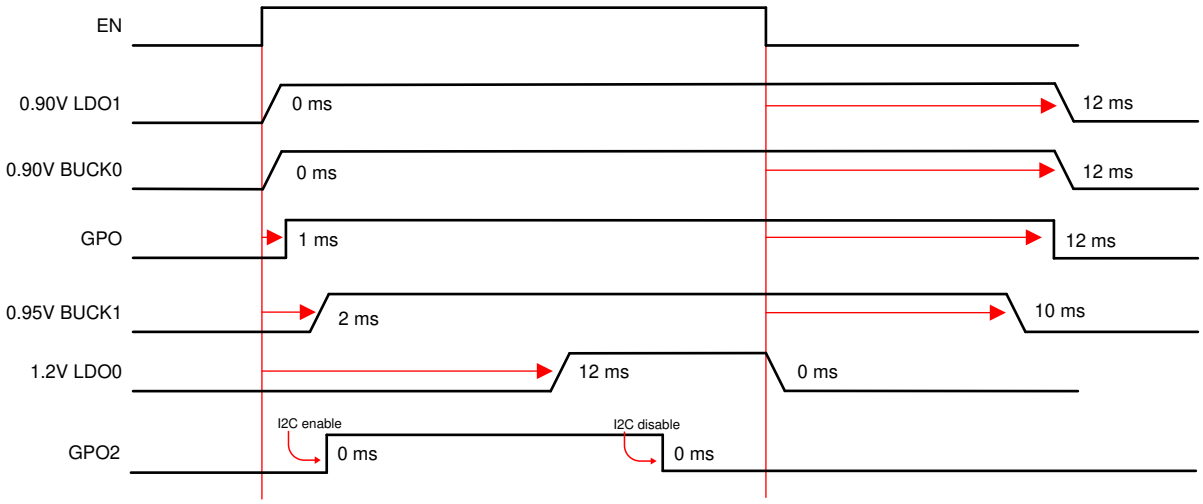


Figure 1. LP873347 Power-up and Power Down Sequence

4 Register Bits Loaded From OTP Memory

Table 8 lists the register bit values loaded from the OTP memory during device start-up.

Table 8. Summary of Control Registers

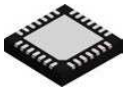
Address	Register Name	Bit	LP873347 Value
0x00	DEV_REV	DEVICE_ID[1:0]	0h
0x01	OTP_REV	OTP_ID[7:0]	47h
0x02	BUCK0_CTRL_1	BUCK0_FPWM	0h
0x02	BUCK0_CTRL_1	BUCK0_EN_PIN_CTRL	1h
0x02	BUCK0_CTRL_1	BUCK0_EN	1h
0x03	BUCK0_CTRL_2	BUCK0_ILIM[2:0]	5h
0x03	BUCK0_CTRL_2	BUCK0_SLEW_RATE[2:0]	4h
0x04	BUCK1_CTRL_1	BUCK1_FPWM	0h
0x04	BUCK1_CTRL_1	BUCK1_EN_PIN_CTRL	1h
0x04	BUCK1_CTRL_1	BUCK1_EN	1h
0x05	BUCK1_CTRL_2	BUCK1_ILIM[2:0]	5h
0x05	BUCK1_CTRL_2	BUCK1_SLEW_RATE[2:0]	4h
0x06	BUCK0_VOUT	BUCK0_VSET[7:0]	39h
0x07	BUCK1_VOUT	BUCK1_VSET[7:0]	43h
0x08	LDO0_CTRL	LDO0_EN_PIN_CTRL	1h
0x08	LDO0_CTRL	LDO0_EN	1h
0x09	LDO1_CTRL	LDO1_EN_PIN_CTRL	1h
0x09	LDO1_CTRL	LDO1_EN	1h
0x0A	LDO0_VOUT	LDO0_VSET[4:0]	4h
0x0B	LDO1_VOUT	LDO1_VSET[4:0]	1h
0x0C	BUCK0_DELAY	BUCK0_SHUTDOWN_DELAY[3:0]	Ch
0x0C	BUCK0_DELAY	BUCK0_STARTUP_DELAY[3:0]	0h
0x0D	BUCK1_DELAY	BUCK1_SHUTDOWN_DELAY[3:0]	Ah
0x0D	BUCK1_DELAY	BUCK1_STARTUP_DELAY[3:0]	2h
0x0E	LDO0_DELAY	LDO0_SHUTDOWN_DELAY[3:0]	0h
0x0E	LDO0_DELAY	LDO0_STARTUP_DELAY[3:0]	Ch
0x0F	LDO1_DELAY	LDO1_SHUTDOWN_DELAY[3:0]	Ch
0x0F	LDO1_DELAY	LDO1_STARTUP_DELAY[3:0]	0h
0x10	GPO_DELAY	GPO_SHUTDOWN_DELAY[3:0]	Ch
0x10	GPO_DELAY	GPO_STARTUP_DELAY[3:0]	1h
0x11	GPO2_DELAY	GPO2_SHUTDOWN_DELAY[3:0]	0h
0x11	GPO2_DELAY	GPO2_STARTUP_DELAY[3:0]	0h
0x12	GPO_CTRL	GPO2_OD	1h
0x12	GPO_CTRL	GPO2_EN_PIN_CTRL	0h
0x12	GPO_CTRL	GPO2_EN	0h
0x12	GPO_CTRL	GPO_OD	1h
0x12	GPO_CTRL	GPO_EN_PIN_CTRL	1h
0x12	GPO_CTRL	GPO_EN	1h
0x13	CONFIG	STARTUP_DELAY_SEL	1h
0x13	CONFIG	SHUTDOWN_DELAY_SEL	1h
0x13	CONFIG	CLKIN_PIN_SEL	0h
0x13	CONFIG	CLKIN_PD	1h
0x13	CONFIG	EN_PD	1h
0x13	CONFIG	TDIE_WARN_LEVEL	0h
0x13	CONFIG	EN_SPREAD_SPEC	0h
0x14	PLL_CTRL	EN_PLL	0h
0x14	PLL_CTRL	EXT_CLK_FREQ[4:0]	1h
0x15	PGOOD_CTRL_1	PGOOD_POL	0h

Table 8. Summary of Control Registers (continued)

Address	Register Name	Bit	LP873347 Value
0x15	PGOOD_CTRL_1	PGOOD_OD	1h
0x15	PGOOD_CTRL_1	PGOOD_WINDOW_LDO	1h
0x15	PGOOD_CTRL_1	PGOOD_WINDOW_BUCK	1h
0x15	PGOOD_CTRL_1	EN_PGOOD_LDO1	1h
0x15	PGOOD_CTRL_1	EN_PGOOD_LDO0	1h
0x15	PGOOD_CTRL_1	EN_PGOOD_BUCK1	1h
0x15	PGOOD_CTRL_1	EN_PGOOD_BUCK0	1h
0x16	PGOOD_CTRL_2	EN_PGOOD_TWARN	0h
0x16	PGOOD_CTRL_2	PG_FAULT_GATES_PGOOD	0h
0x16	PGOOD_CTRL_2	PGOOD_MODE	0h
0x20	TOP_MASK_1	PGOOD_INT_MASK	1h
0x20	TOP_MASK_1	SYNC_CLK_MASK	1h
0x20	TOP_MASK_1	TDIE_WARN_MASK	1h
0x20	TOP_MASK_1	I_MEAS_MASK	1h
0x21	TOP_MASK_2	RESET_REG_MASK	1h
0x22	BUCK_MASK	BUCK1_PGF_MASK	1h
0x22	BUCK_MASK	BUCK1_PGR_MASK	1h
0x22	BUCK_MASK	BUCK1_ILIM_MASK	1h
0x22	BUCK_MASK	BUCK0_PGF_MASK	1h
0x22	BUCK_MASK	BUCK0_PGR_MASK	1h
0x22	BUCK_MASK	BUCK0_ILIM_MASK	1h
0x23	LDO_MASK	LDO1_PGF_MASK	1h
0x23	LDO_MASK	LDO1_PGR_MASK	1h
0x23	LDO_MASK	LDO1_ILIM_MASK	1h
0x23	LDO_MASK	LDO0_PGF_MASK	1h
0x23	LDO_MASK	LDO0_PGR_MASK	1h
0x23	LDO_MASK	LDO0_ILIM_MASK	1h

Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

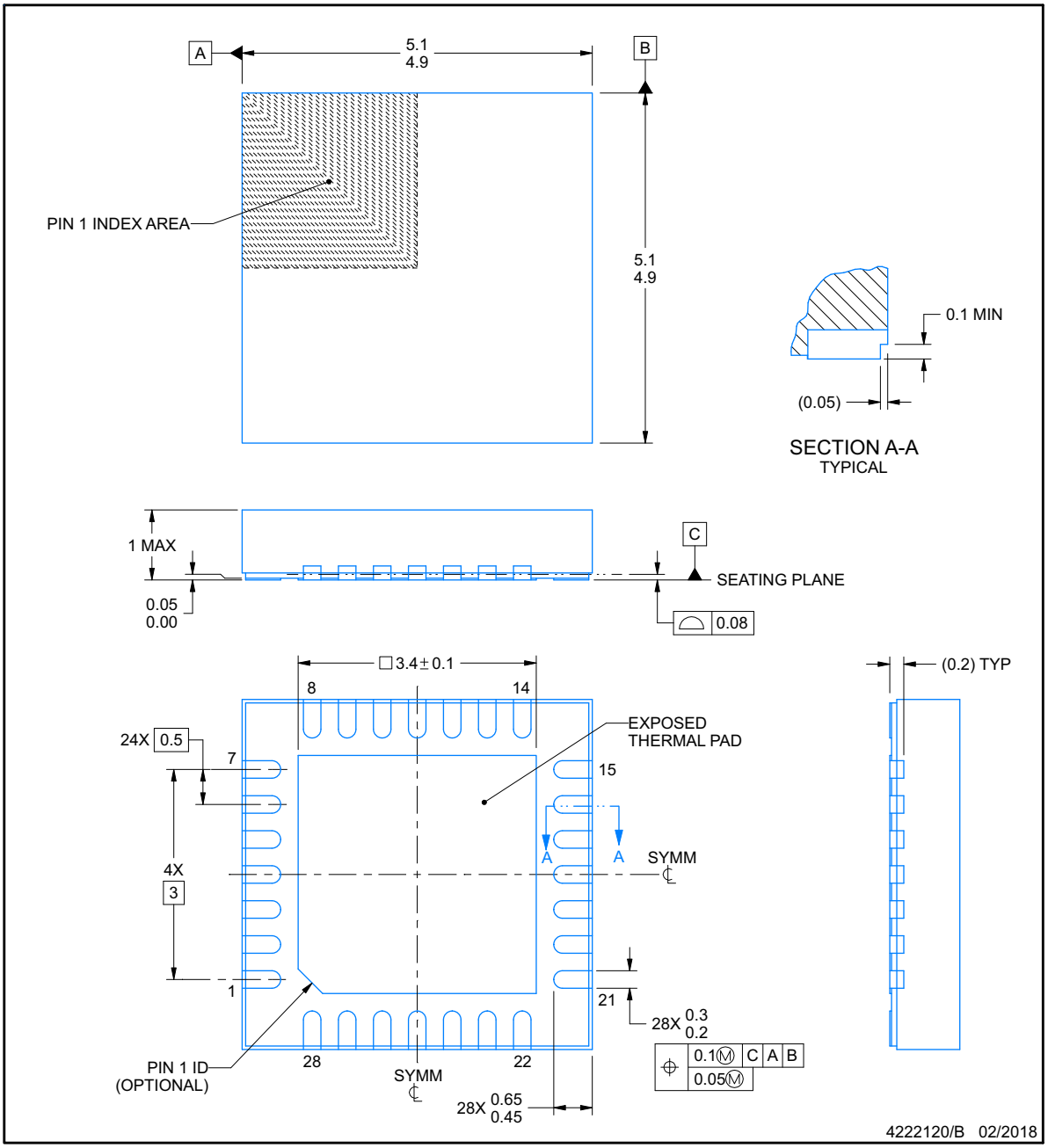


PACKAGE OUTLINE

RHD0028W

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



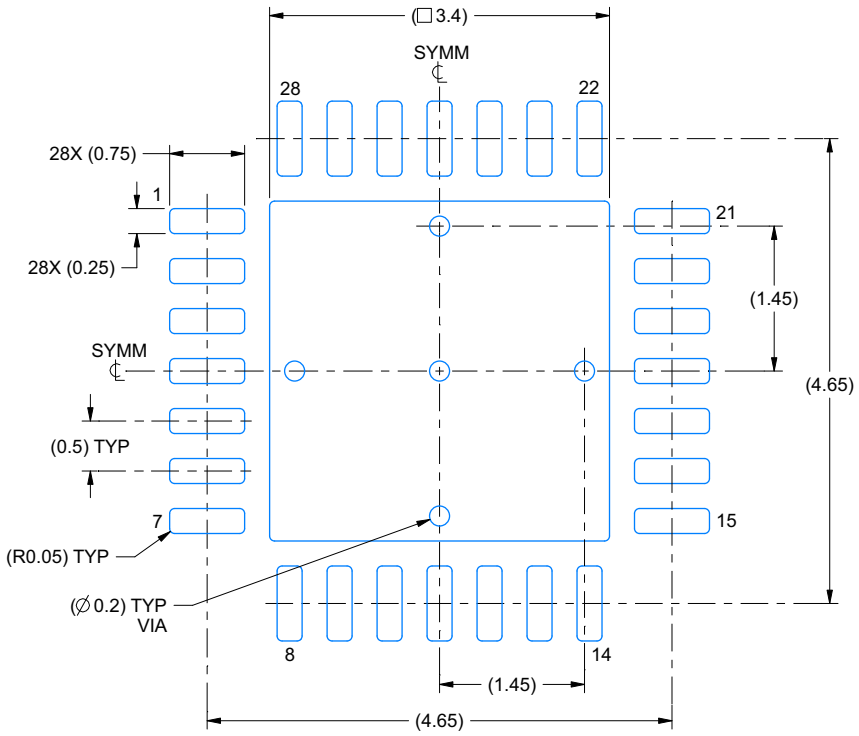
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

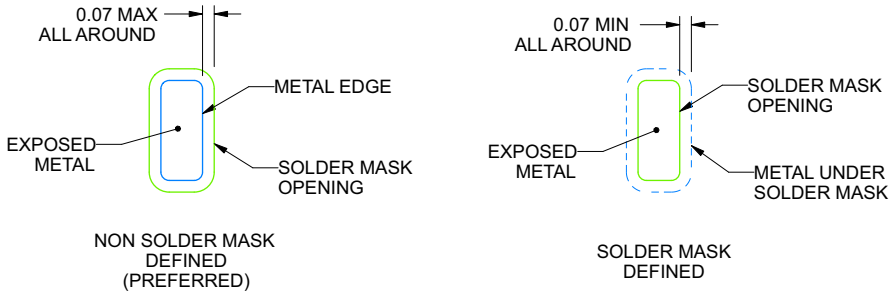
EXAMPLE BOARD LAYOUT

RHD0028W **VQFN - 1 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4222120/B 02/2018

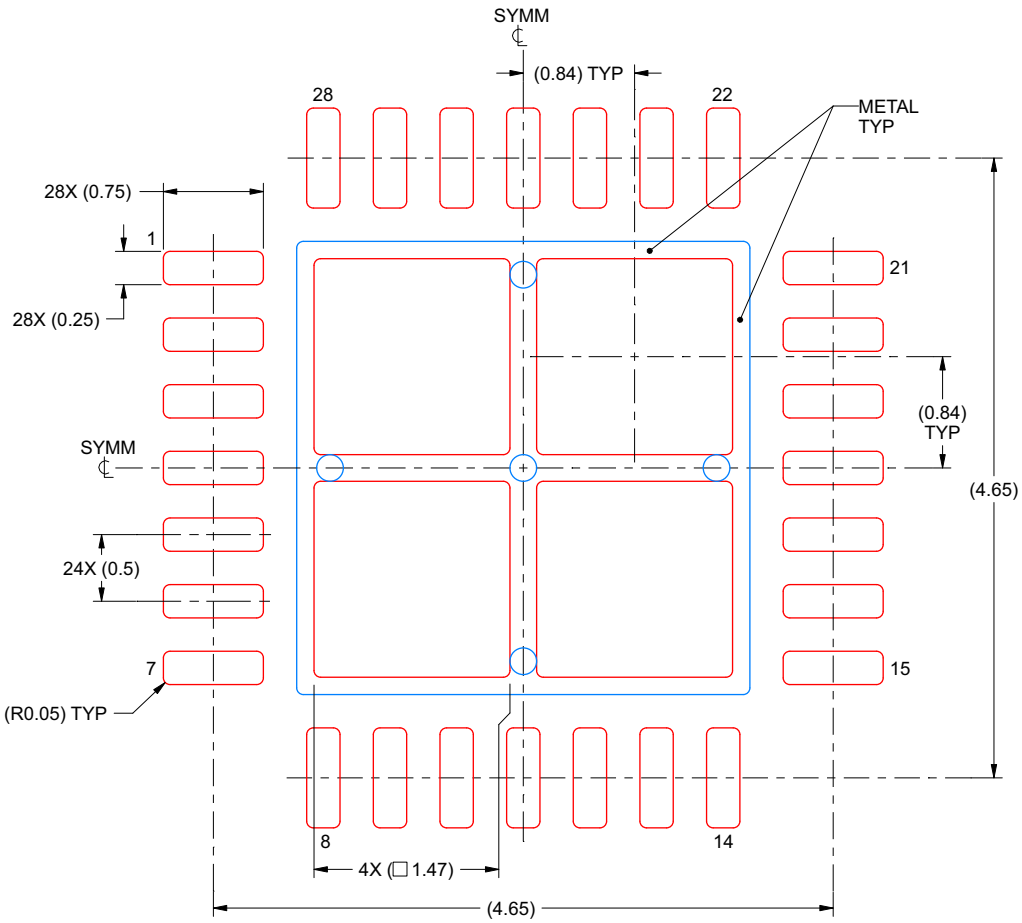
NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

RHD0028W **VQFN - 1 mm max height**

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
75% PRINTED SOLDER COVERAGE BY AREA
SCALE:20X

4222120/B 02/2018

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

1 Packaging Information

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (3)	MSL Peak Temp (4)	Op Temp (°C)	Device Marking (5) (6)
LP873347RHDR	ACTIVE	VQFN	RHD	28	3000	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	-40 to 125	LP8733 47RHD
LP873347RHDT	ACTIVE	VQFN	RHD	28	250	Green (RoHS & no Sb/Br)	CU SN	Level-2-260C-1 YEAR	-40 to 125	LP8733 47RHD

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PRE_PROD Unannounced device, not in production, not available for mass market, nor on the web, samples not available.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

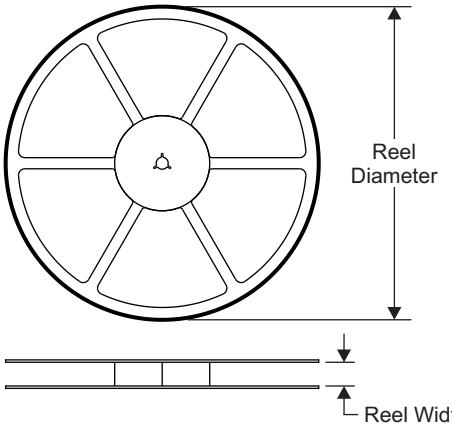
(4) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(5) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device

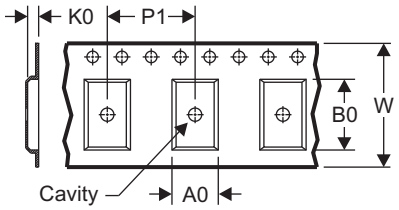
(6) Multiple Device markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

1.1 Tape and Reel Information

REEL DIMENSIONS

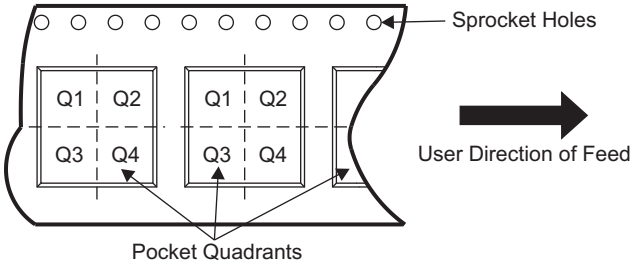


TAPE DIMENSIONS



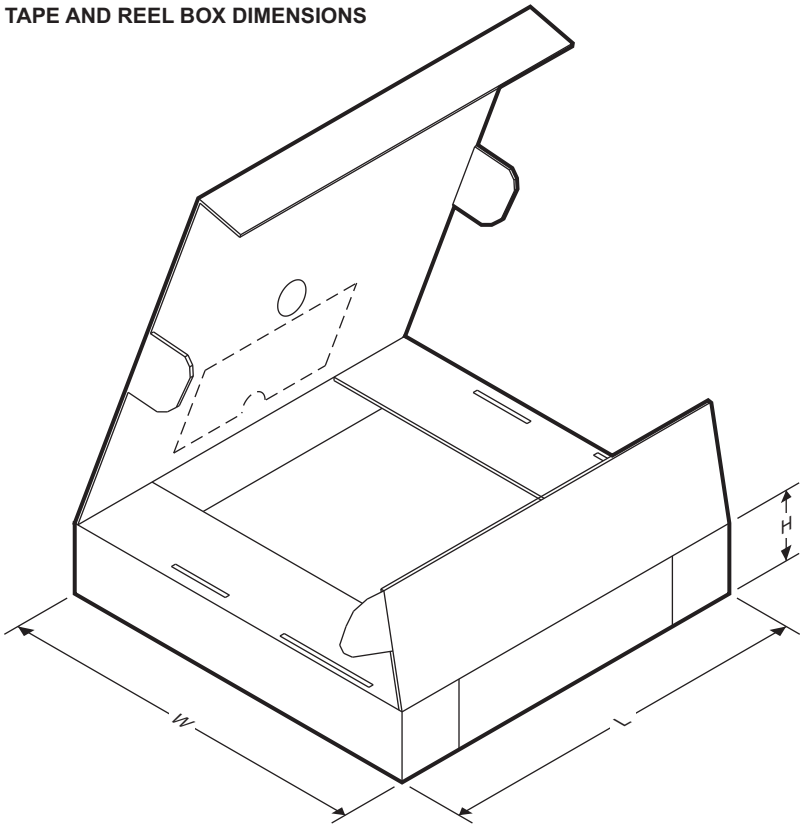
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LP873347RHDR	VQFN	RHD	28	3000	330.0	12.4	5.25	5.25	1.1	8.0	12.0	Q2
LP873347RHDT	VQFN	RHD	28	250	330.0	12.4	5.25	5.25	1.1	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LP873347RHDR	VQFN	RHD	28	3000	370.0	355.0	55.0
LP873347RHDT	VQFN	RHD	28	250	370.0	355.0	55.0

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